APPLICA	BLE STAN	DARD								
OPERATING TEMPERATUR		E RANGE	-35 °C TO +85 °C(NOTE1)			STORAGE TEMPERATURE RANGE		-10 °C TO +60 °C(NO)
DATING	TEMPERATURE RANGE OPERATING		40% TO 80% (NOTE2)			STORAGE		40% TO 70% (NO		
RATING	HUMIDITY RANGE		H			IUMIDITY RANGE				
	VOLTAGE		250 V AC CO		_	INECTOR		DF1E-*S-2.5C		
	CURRENT		AWG20 TO 24: 3A			VOLTAGE		AC 30V		
			AWG26: 2A AWG28: 1A		UL, CSA	٨		AWG20 TO 22: 3		
		AWG30: 0.5A			CURRENT		AWG24 TO 28: 1A AWG30: 0.5A			
			SPEC	IFICAT	LIONS	3		AWGSO: U. S	A	
17	EM		TEST METHOD				REQU	JIREMENTS	QT	AT
CONSTR	RUCTION	•								
	XAMINATION		Y AND BY MEASURING IN	ISTRUMEN	IT. AC	CORDING	TO DF	RAWING.	X	Х
MARKING			CONFIRMED VISUALLY.							X
CONTACT RE	IC CHARA			⊔ →\	lao .	O MAY				
	EVEL METHOD.	20 mV MAX, 1 mA(DC OR 1000 Hz). 30 mΩ MAX.							Х	-
INSULATION		500 V DC.				1000 MΩ MIN.			Х	_
RESISTANO VOLTAGE F		650 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				
MECHAN	110 41 0114								X	_
MECHANICA MECHANICA	NCAL CHA			CTIONS	1	CONTACT	DECI	STANCE: 20 mg MAV		
OPERATION		50TIMES INSERTIONS AND EXTRACTIONS.				 CONTACT RESISTANCE: 30 mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS 				_
						OF PARTS.				<u> </u>
VIBRATION						 NO ELECTRICAL DISCONTINUITY OF 1 μs. NO DAMAGE, CRACK OR LOOSENESS 			Х	_
			490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES							
			IRECTIONS.						Х	_
RAPID CHA			ACTERISTICS ATURE -55→ 5 TO 35→+8	5→ 5 TO 3	5 °C (1)	CONTACT	DECL	STANCE: 30 mΩ MAX.	1	1
TEMPERATURE		TIME $30 \rightarrow 5 \text{ MAX} \rightarrow 30 \rightarrow 5 \text{ MAX} \text{ min}$							Х	_
		l				③ NO DAMAGE, CRACK OR LOOSENESS				
DAMP HEAT E		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.				OF PARTS		STANCE: 30 mΩ MAX.		
(STEADY STATE)		EXT GOLD XI 40 ± 2 6, 66 10 66 76, 66 II.			_	$\begin{tabular}{ll} \hline \end{tabular}$ INSULATION RESISTANCE: 500 M Ω MIN.				-
							③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			
RESISTANCE TO 1)		1) AUTOMATIC SOLDERING (FLOW)				NO DEFORMATION OF CASE OF				
SOLDERING HEAT		'				EXCESSIVE LOOSENESS OF THE TERMINALS.				-
		,	ERING IRON TEMPERATUI	RE:300 °C	Э,					
			ERING TIME: 3 sec.							
SOLDERABILITY S		NO STRENGTH ON CONTACT. SOLDERED AT SOLDER TEMPERATURE,			SO	SOLDER SHALL COVER A MINIMUM OF				
235 ℃		235 °C F0	FOR INSERTION DURATION, 5 s.			95 % OF THE SURFACE BEING IMMERSED			X	-
REMARKS NOTE1: INCL		ERATURE F	RISING BY CURRENT.							
NOTE2:NO C	ONDENSING.		ONG TERM STORAGE FOR U	INILISED DDC	אחווחר					
BEFO	RE PCB ON BOA	ARD. AFT	ER PCB BOARD,OPERATING 1	TEMPERATU	JRE AND					
- T			OR INTERIM STORAGE DURIN					OUES:		T F
COUN	II DE	SCRIPTIO	ON OF REVISIONS		DESIGNE	ט		CHECKED	DA	TE
Unless otherwise specified, refer to II			EC 60512.	[APPRO	DVED	KI. AKIYAMA	15 0	5. 29
						CHEC		TS. FUKUSHIMA	+	5. 29
						DESIGN		TS. KUMAZAWA	1	5. 29
				1		DRA	WN	MI. SAKIMURA	15.0	5. 28
Note QT:Q	ualification Tes	cation Test AT:Assurance Test X:Applicable Test				VING NO.		ELC-161951-36-00		
КS	SF	PECIFI	CATION SHEET		PART NO	D		DF1E-*P-2. 5DS (36)		
1.7			ECTRIC CO., LTD.		CODE NO	D.	CL541 Z		Δ	1/1
FORM HDOO11			,						_	•

